



Walden C. Rhines
Chairman

EDA OS Industry Roadmap – Now Live

EDA CONSORTIUM Where Electronics Begins™

About Us EDA Industry Market Stats News Events Resources Join

Resources
EDA Industry OS Roadmap

Support Plans of Consortium Members

This initiative debuts with links to leading public and private EDA companies, representing over 80% of the industry's revenue.

Baseline EDA Industry OS Roadmap

Note

- EDA tool suppliers may exceed the Roadmap baselines.
- Future dates are subject to change.

EDA Industry OS Roadmap includes a baseline of OS support timelines. Today the Roadmap covers EDA vendor support guidelines for the following OS versions:

Compute Platform	Operating System
Sun Ultra Sparc	Solaris 8 Solaris 9 Solaris 10
PA-RISC 2.0 (32/64 bit)	HP-UX 11.0 HP-UX 11i Version 1 HP-UX 11i Version 3
X86 (32-bit Windows)	Windows 2000 Windows XP Professional Windows Server 2003
X86 (32-bit Linux)	Red Hat Enterprise Linux 3 Red Hat Enterprise Linux 4
Itanium 2 (64-bit)	Red Hat Enterprise Linux 2.1 Red Hat Enterprise Linux 3 Red Hat Enterprise Linux 4
AMD64 (32/64 bit)	Red Hat Enterprise Linux 3 Red Hat Enterprise Linux 4

Guideline for UltraSPARC - Solaris

Guideline for PA-RISC 2.0 - HP-UX

Guideline for X86 32-bit - Windows

Guideline for X86 32-bit - Linux

Guideline for Itanium 2 64-bit - Linux

Guideline for AMD64 - Linux

OS Version	OS Vendor GA	EDAC Guideline Start of Support	OS Vendor Planned EoS	EDAC Guideline End of Support
RHEL 3	October 2003	April 2004	None Announced - estimate May 2006	May 2006
RHEL 4	November 2004 (estimate)	May 2005	None Announced	None Announced

2004 2005 2006 2007

Red Hat Enterprise Linux 3

Red Hat Enterprise Linux 4

EDAC AMD64 (32/64) Linux Support Guideline

- EDA tool suppliers may exceed the Roadmap baselines.
- Future dates are subject to change.
- EDA tool introduction may be phased on this emerging platform. All EDA tool suppliers may not begin support with Red Hat Enterprise Linux 2.1.

Back

Visit <http://www.edac.org>

Recently Simplified EDA Export Regulation

3.D.3 Classification – Ratified at the December 2003 Wassenaar Plenary

3.D.3. ‘Physics-based’ simulation “software” specially designed for the “development” of lithographic, etching or deposition processes for translating masking patterns into specific topographical patterns in conductors, dielectrics or semiconductor materials.

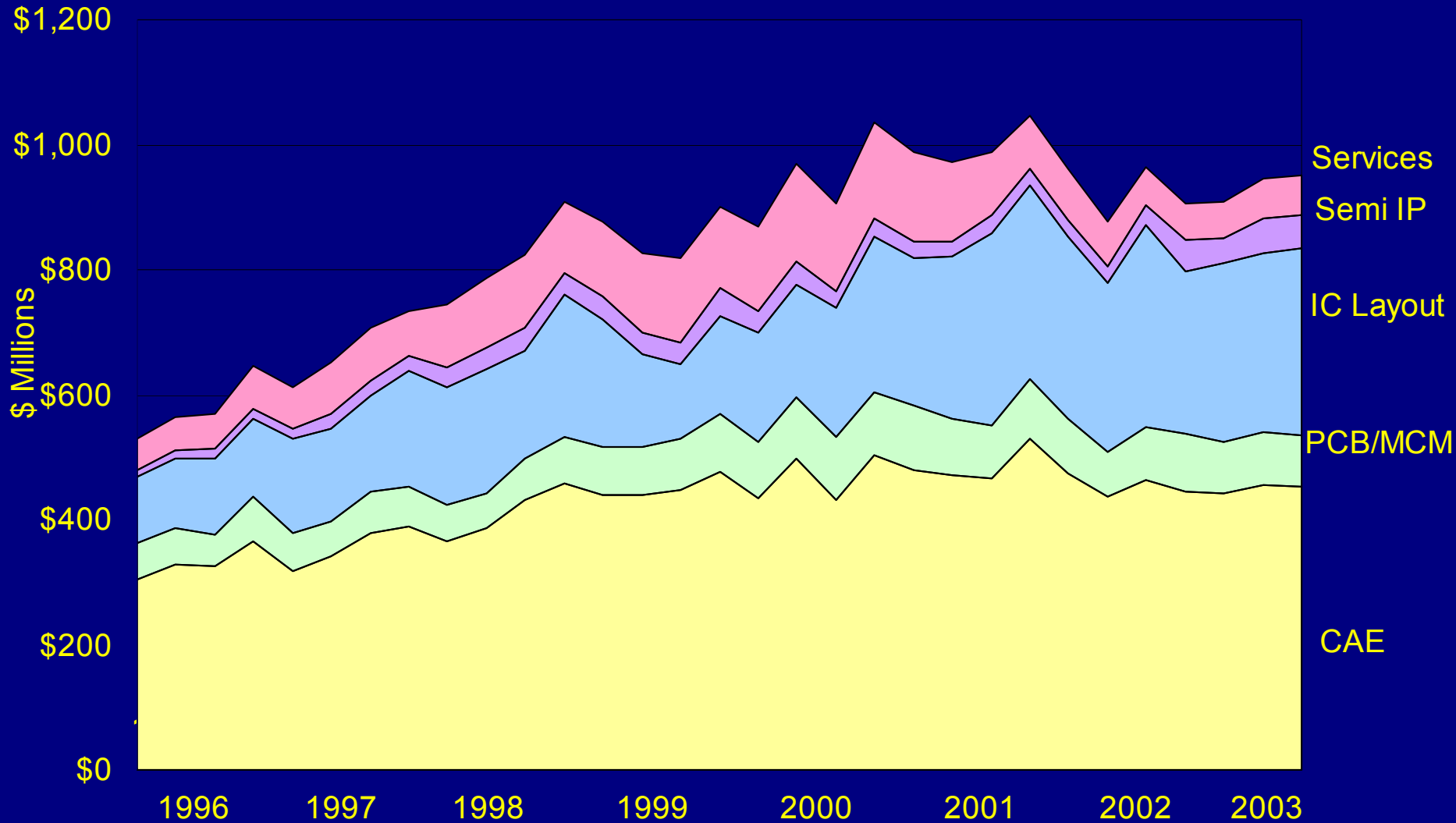
Technical Note: ‘Physics-based’ in 3.D.3. means using computations to determine a sequence of physical cause and effect events based on physical properties (e.g., temperature, pressure, diffusion constants and semiconductor materials properties).

Note 1. Libraries, design attributes or associated data for the design of semiconductor devices or integrated circuits are considered as “technology”.

Bi-Annual Elections April 19, 2004

- Nine Consortium directors
- Each voting member company may nominate one candidate who must be CEO or COO of a voting member company.
- **Nominations due: Monday, March 8, 2004**

MSS Reports 1% Sequential Revenue Growth And 4% Employment Growth for Q3 2003



IBDA

WHERE

ELECTRONICS

BEGINS